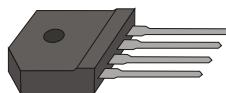


FEATURES

- * Ideal for printed circuit board
- * Low forward voltage
- * Low leakage current
- * Polarity: marked on body
- * Mounting position: Any

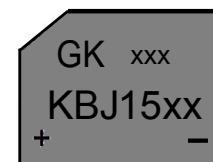


VOLTAGE RANGE

50 to 1000 Volts

CURRENT

15.0 Amperes



LOGO

GK xxx

CODE

KBJ 15 xx

IF

VR Voltage

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.

Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	KBJ15005	KBJ1501	KBJ1502	KBJ1504	KBJ1506	KBJ1508	KBJ1510	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Current @T _c =100°C				15.0				A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)				240				A
Maximum Forward Voltage Drop per Bridge Element at 7.5A D.C.				1.05				V
Maximum DC Reverse Current Ta=25°C				10				µA
at Rated DC Blocking Voltage Ta=125°C				500				µA
Typical Junction Capacitance (Note 1)				60				PF
Typical Thermal Resistance R _{jc} (Note 2)				0.8				°C/W
Operating Temperature Range, T _j				-55 — +150				°C
Storage Temperature Range, T _{stg}				-55 — +150				°C

NOTES:

1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2. Thermal Resistance from Junction to Case with device mounted on 300mm x 300mm x 1.6mm Cu Plate Heatsink.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

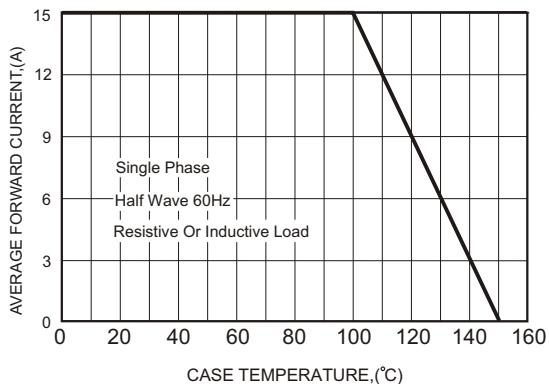


FIG.2-TYPICAL FORWARD CHARACTERISTICS

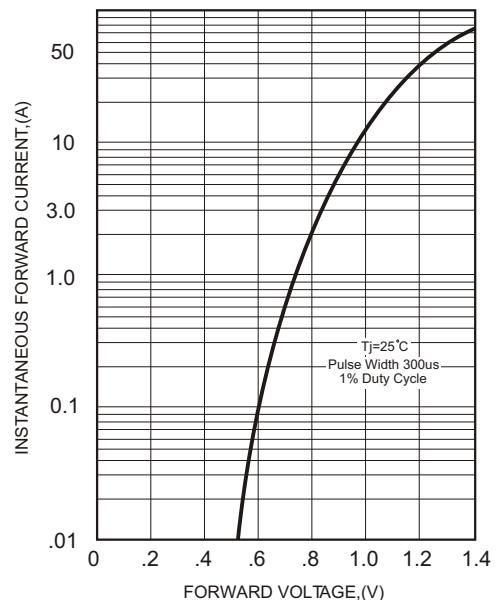


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

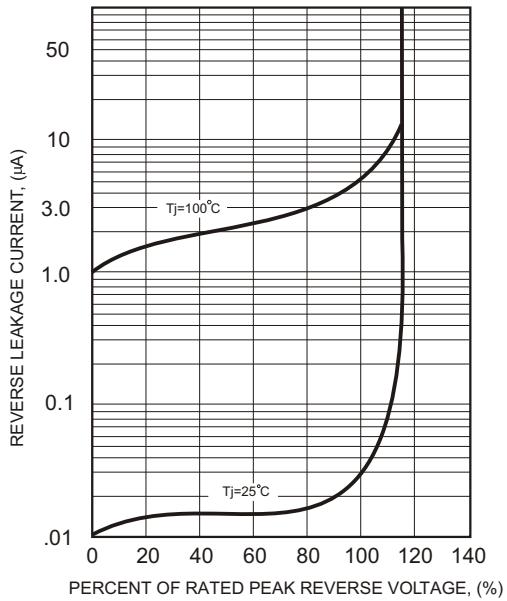
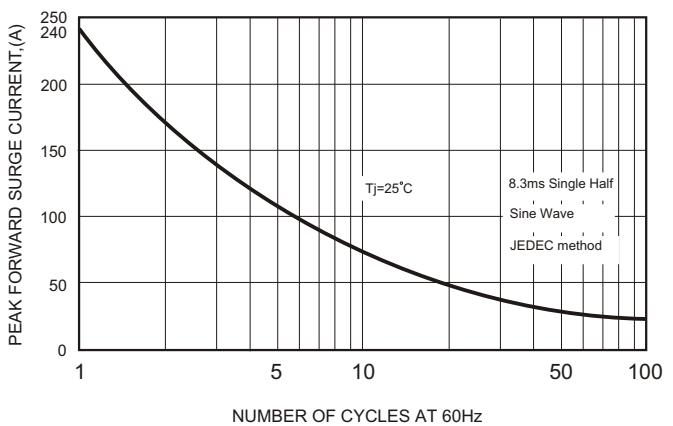
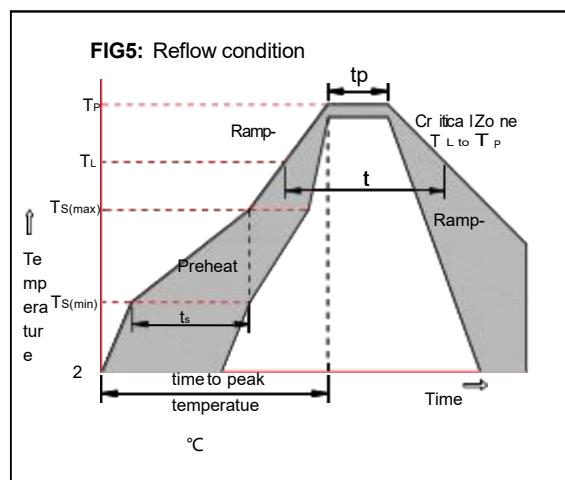


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_p)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

